



ABSTRACT

By an electronic component mounting method for electrically connecting bumps to board electrodes, in a contact process for placing a thermosetting resin in a liquid glob state on the board surface and bringing the lower surface of the electronic component in contact with the thermosetting resin, the bumps are pressurized against the electrodes in positional alignment in a liquid glob distribution state where one portion of the liquid glob is arranged inside an electronic component mounting region and a remaining portion greater in liquid measure than the portion is arranged outside the electronic component mounting region. The thermosetting resin enters into a gap between the electronic component and the board by capillarity in a thermocompression bonding process. This prevents voids occurring in the sealing resin, reinforces bonded portions of bumps and electrodes with thermally cured thermosetting resin, thereby preventing bonded portion breakage due to thermal stress generated during a cooling process.